

ABSTRACT:

A method of manufacturing an electronic device (10) is proposed that comprises an insulating body (2) with at a surface a conductive pattern (1). According to the invention, a carrier (3) is provided with a first layer (4) and a second layer (5), which layers (4, 5) comprise different materials. After reshaping of the carrier (3) from the side of the second layer (5), insulating material (2) is provided at the side of the second layer (5), and the first layer (4) is removed, therewith providing the insulating body (2) with the conductive pattern (1). The reshaping may be done, for example, by bending or by forcing. The resulting body (2) is very suitable for use in modules, as part of a compact camera. Its shape may be defined with a mold.

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Fig. 14